SURFACE PROTECTIVE FILM PEELING METHOD AND SURFACE PROTECTIVE FILM PEELING APPARATUS

ABSTRACT OF THE DISCLOSURE

A surface protective film peeling method for peeling off a surface protective film (11) attached on the surface of a wafer (20) is disclosed. The wafer is supported on a movable table (31) with the surface protective film directed up, and an incision (15) is formed at one end (28) of the surface protective film along the surface of the wafer, the peeling tape is attached on the front surface of the portion in which the incision is formed, at one end of the surface protective film, the movable table is moved in the direction toward the one end from the other end (29) of the wafer, and the surface protective film is thus peeled off from the front surface of the wafer. As a result, the surface protective film can be peeled without causing cuts or cracks, etc. in the wafer. Also, in the case where the movable table is moved while holding the portion in which the incision is formed, the surface protective film can be peeled off without using the peeling tape.

Fig. 5